



SOT618-6

plastic thermal enhanced very thin quad flat package; no leads; 40 terminals; body 6 x 6 x 0.85 mm

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN40
Package type industry code	HVQFN40
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-220
JEITA package outline code	- - -
Mounting method type	S (surface mount)
Issue date	4-3-2009

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	5.9	-	6	6.1	mm
E	package width	5.9	-	6	6.1	mm
A	seated height	[tbd]	-	0.85	1	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	40	-	

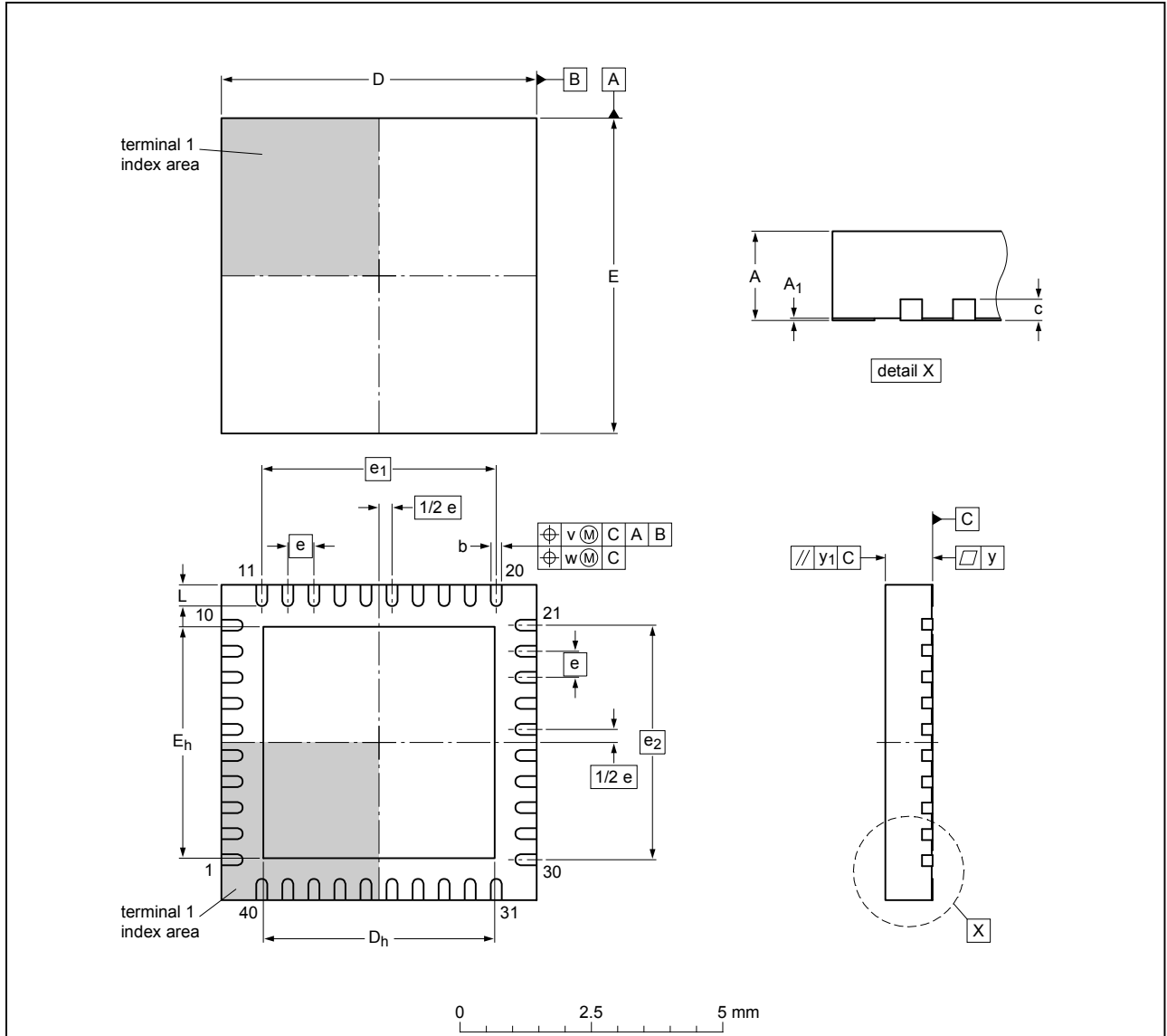


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2. Package outline

HVQFN40: plastic thermal enhanced very thin quad flat package; no leads; 40 terminals; body 6 x 6 x 0.85 mm

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Dimensions

Unit	A ⁽¹⁾	A ₁	b	c	D ⁽¹⁾	D _h	E ⁽¹⁾	E _h	e	e ₁	e ₂	L	v	w	y	y ₁
max	1.00	0.05	0.30		6.1	4.55	6.1	4.55				0.5				
mm nom	0.85	0.02	0.21	0.2	6.0	4.40	6.0	4.40	0.5	4.5	4.5	0.4	0.1	0.05	0.05	0.1
min	0.80	0.00	0.18		5.9	4.25	5.9	4.25				0.3				

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

sot618-6_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT618-6		MO-220	---		09-02-23 09-03-04

Fig. 1. Package outline HVQFN40 (SOT618-6)

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3. Legal information

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Date of release: 8 February 2016
